

Title (en)  
Polishing peripheral portions of wafers

Title (de)  
Polieren der Randbereiche von Wafers

Title (fr)  
Polissage des parties périphériques de wafers

Publication  
**EP 0745456 A1 19961204 (EN)**

Application  
**EP 96303484 A 19960516**

Priority  
JP 15381395 A 19950529

Abstract (en)  
A method and apparatus for mirror-polishing a peripheral portion of a wafer (W) carries out a first polishing step (2, 12, 13, 14) for polishing the peripheral portion of the wafer (W) by using tape (T) having abrasive grains thereon, and a second polishing step (3) for thereafter polishing the peripheral portion of the wafer (W) by using a buff (22, 23, 24) with an abrasive material. <IMAGE>

IPC 1-7  
**B24B 9/06**

IPC 8 full level  
**B24B 9/06** (2006.01)

CPC (source: EP KR)  
**B24B 9/065** (2013.01 - EP); **H01L 21/304** (2013.01 - KR)

Citation (search report)

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Designated contracting state (EPC)  
DE FR GB

DOCDB simple family (publication)  
**EP 0745456 A1 19961204**; **EP 0745456 B1 20010919**; DE 69615273 D1 20011025; DE 69615273 T2 20020627; KR 960043006 A 19961221; TW 303487 B 19970421

DOCDB simple family (application)  
**EP 96303484 A 19960516**; DE 69615273 T 19960516; KR 19960019606 A 19960528; TW 85105672 A 19960514